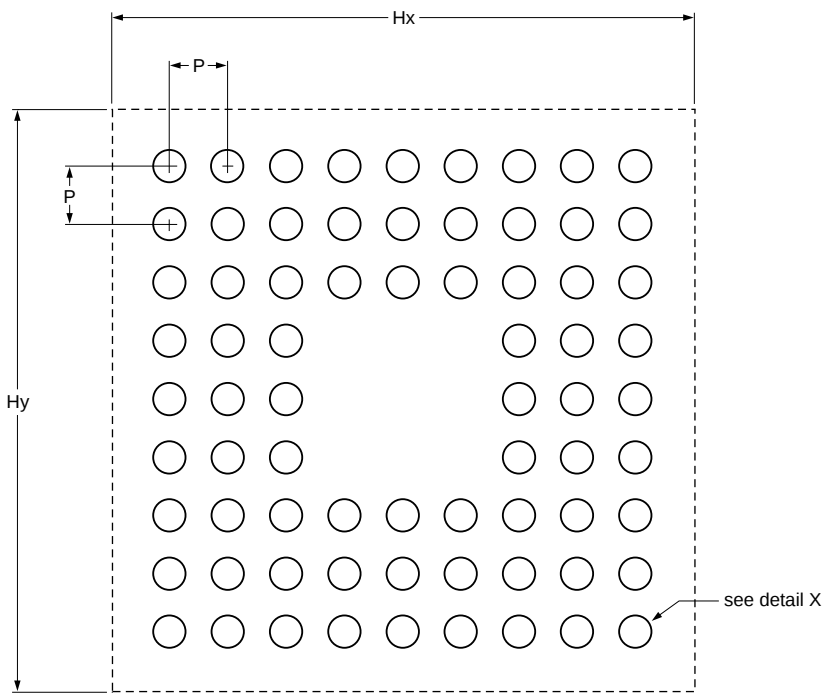


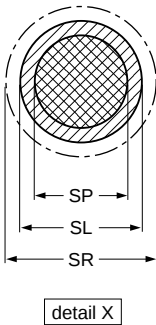
Footprint information for reflow soldering of BGA553 package

SOT589-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- - - - - solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	38.075	38.075